

Triangulating tunneling resonances in a point contact



Nathan Bishop¹

Carlos Borrás Pinilla^{2,3}, Harold Stalford², Ralph Young¹,
Greg Ten Eyck¹, Joel Wendt¹, Kevin Eng^{1,4},
Michael Lilly¹, Malcolm Carroll¹

1. Sandia National Laboratories

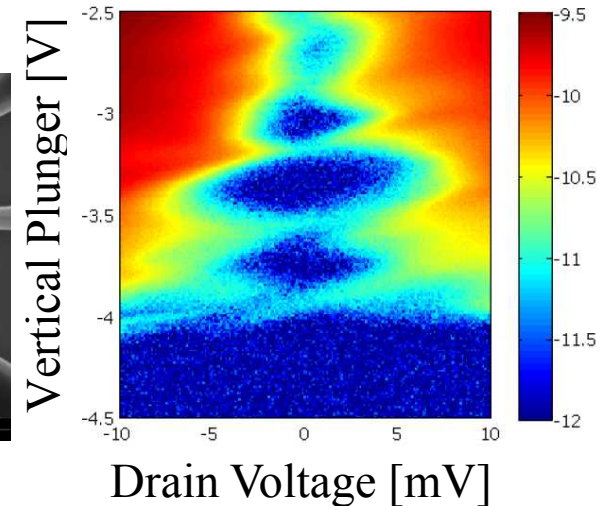
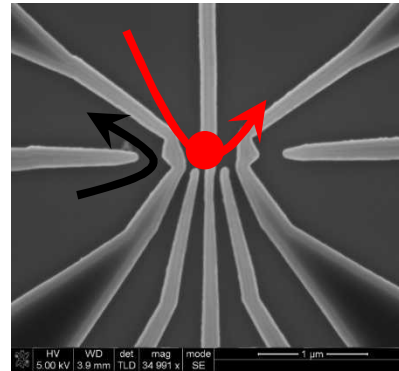
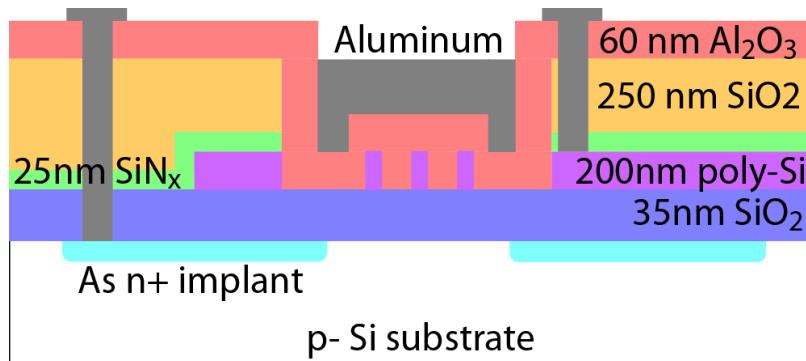
2. University of Oklahoma

3. Universidad Industrial de Santander-Colombia

4. HRL Laboratory

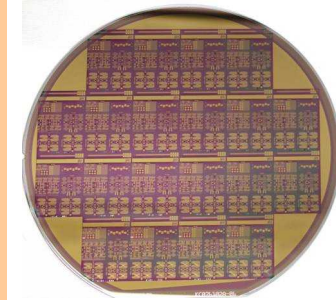
This work was supported by the Laboratory Directed Research and Development program at Sandia National Laboratories. Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company, for the United States Department of Energy's National Nuclear Security Administration under Contract DE-AC04-94AL85000.

Si MOS devices at Sandia



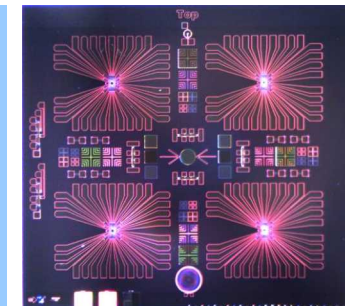
- Oxide growth
- Polysilicon deposition and patterning
- Ohmic contact implant and anneal
- Nitride and pre-metal dielectric dep.
- Silicide and metallization

Front end

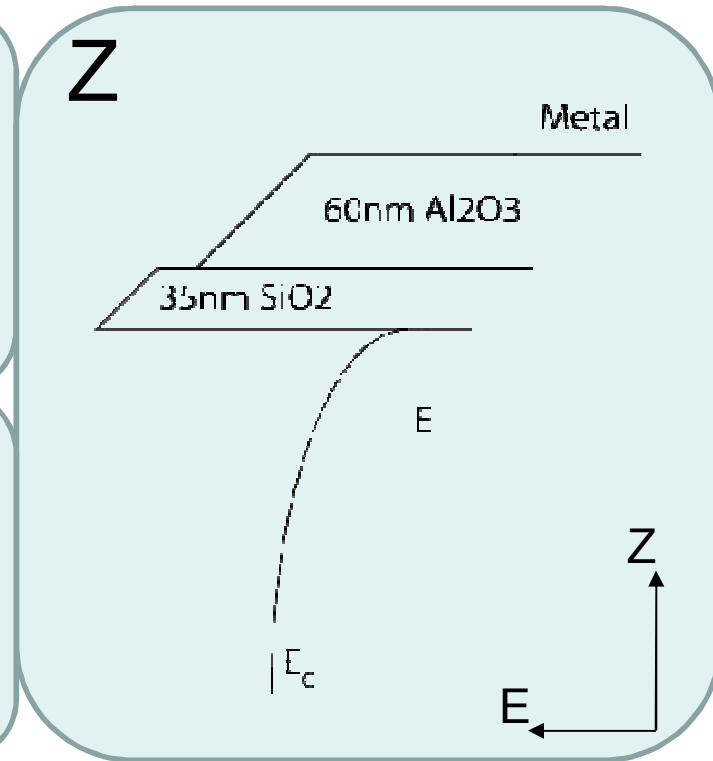
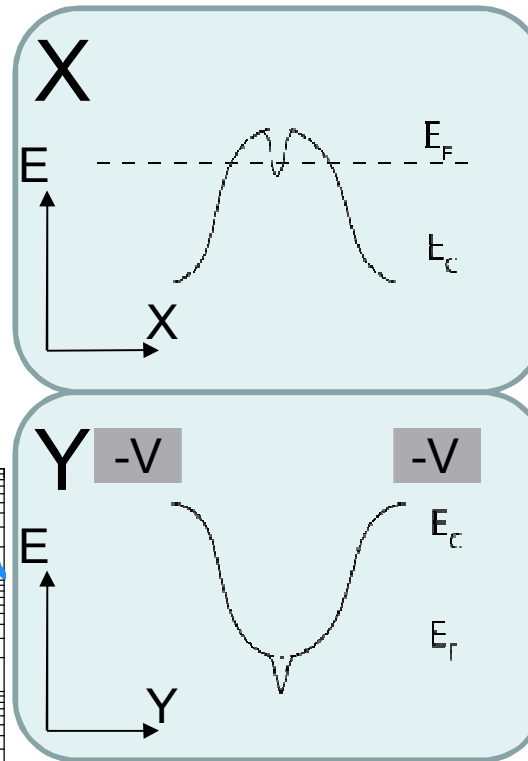
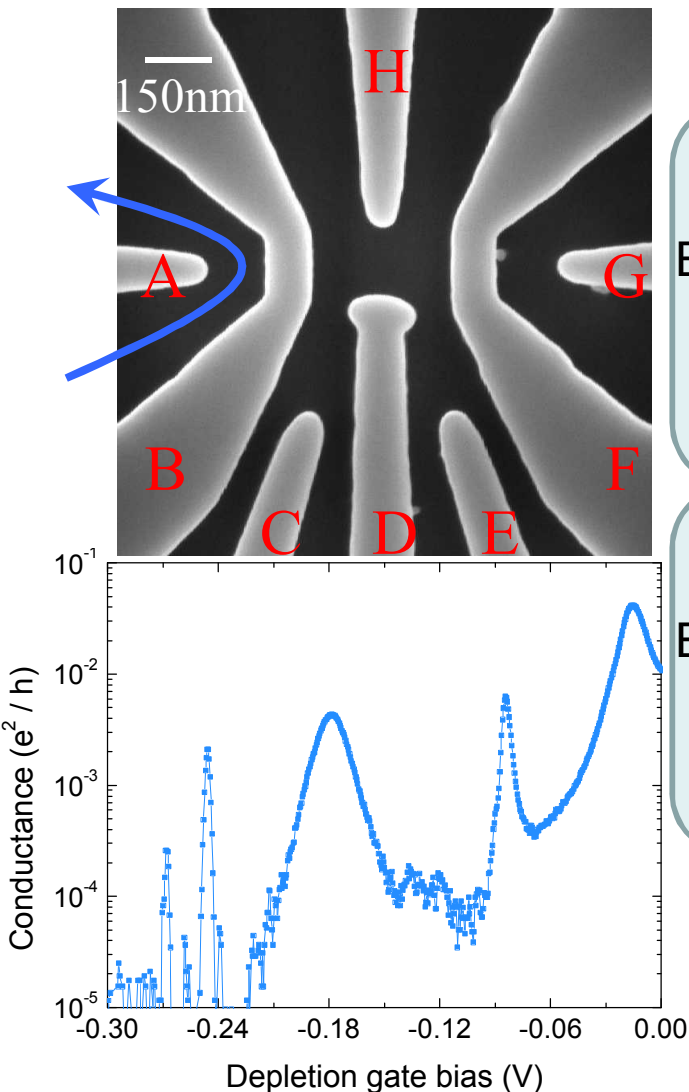


- E-beam litho and polysilicon patterning
- **Implant dopant atoms**
- Strip metal and re-oxidize polysilicon
- Second dielectric (ALD Al₂O₃) dep.
- Final metallization

Back end



Constriction with antimony donors implanted

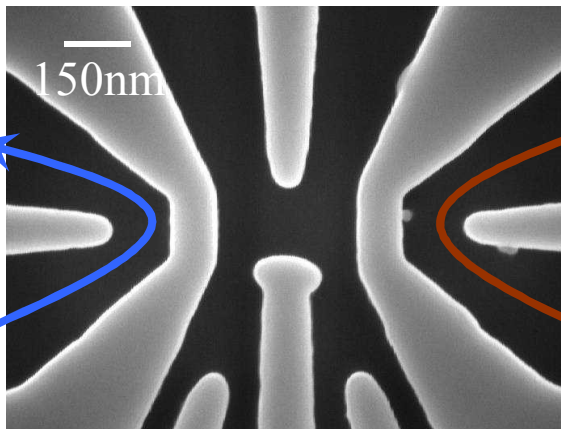


100 keV antimony implant
 $T \sim 250\text{mK}$, $V_{sd} = 0.5 \text{ mVrms}$

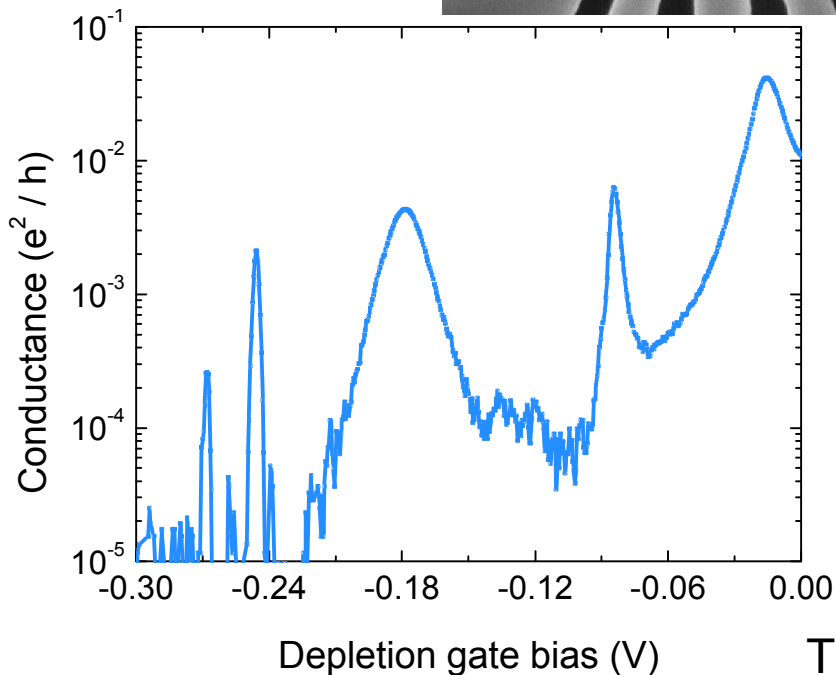
Control vs. implanted

Antimony allows
high temperature
post-implant
processing.

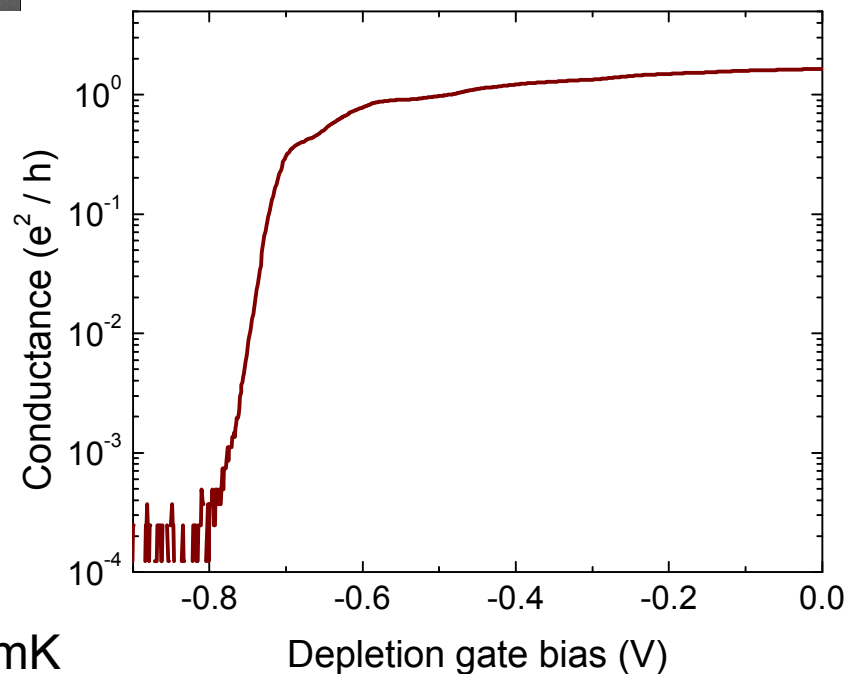
100 keV antimony
 $4 \times 10^{11} \text{ cm}^{-2}$ dose



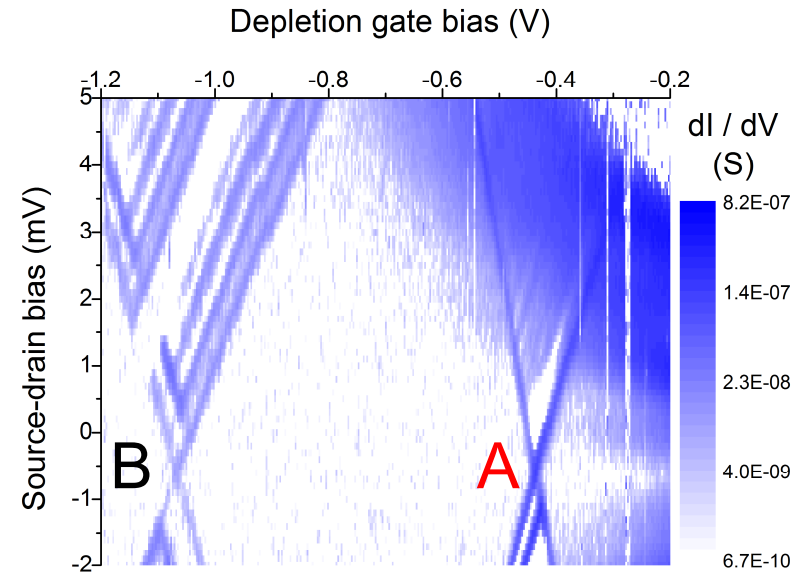
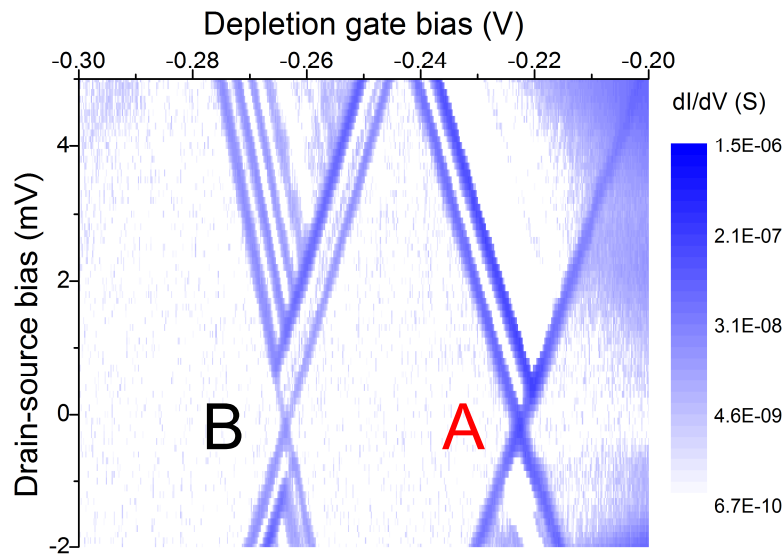
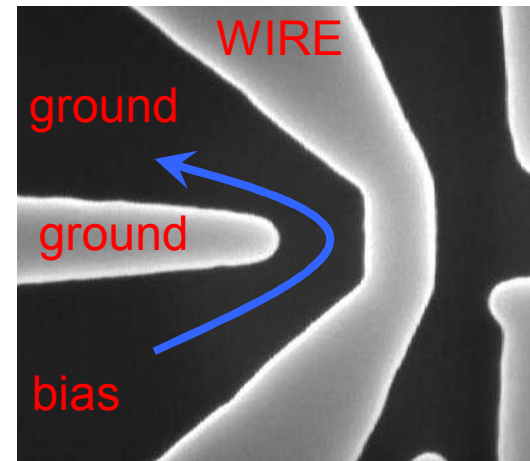
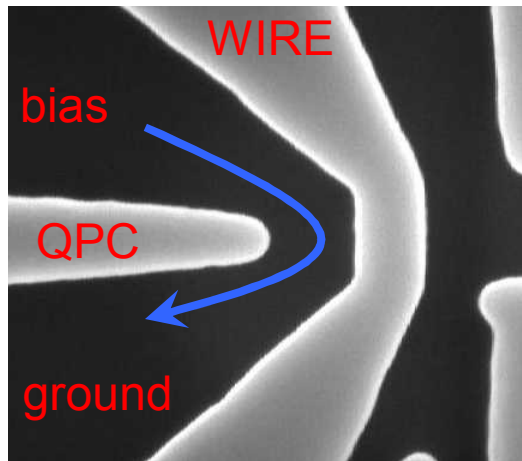
Sample type	Q_{fb} (q/cm^2)	D_{it} ($\text{q}/\text{cm}^2\text{eV}$)
Normal process	$+ 5 \times 10^{10}$	1×10^{10}
Silicon implant + RTA (Donor device equivalent dose)	$+ 3 \times 10^{11}$	2×10^{11}
Silicon implant + reoxidation	$+ 1 \times 10^{11}$	1×10^{10}



$T \sim 250\text{mK}$
 $V_{sd} = 0.5 \text{ mVrms}$

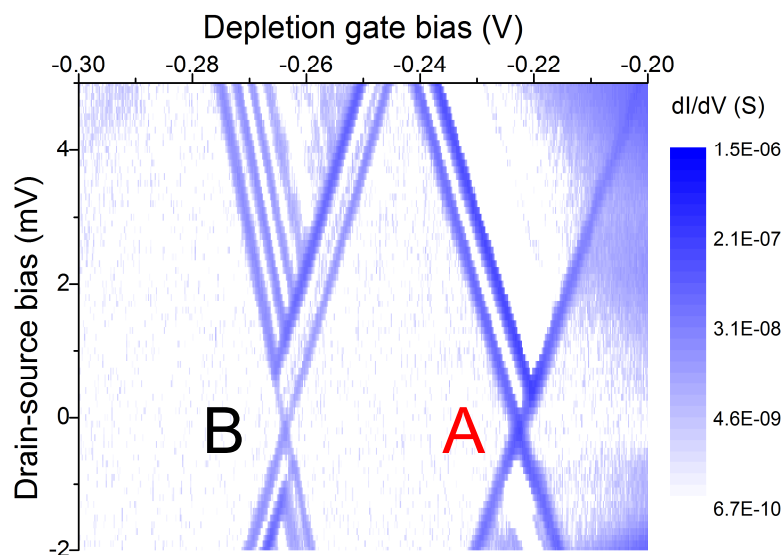
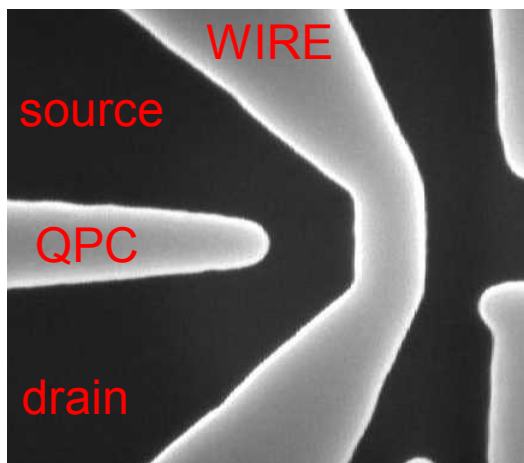


Extracting capacitance



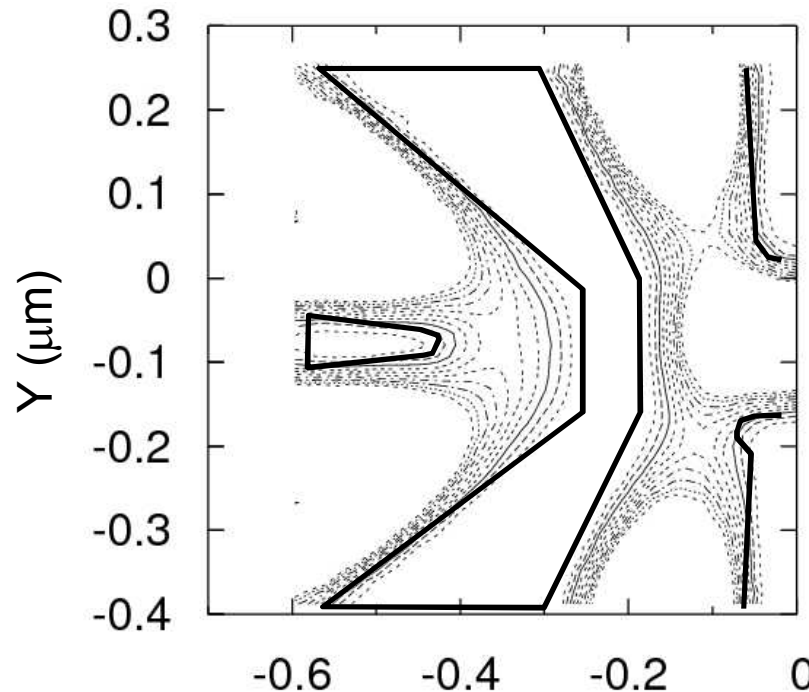
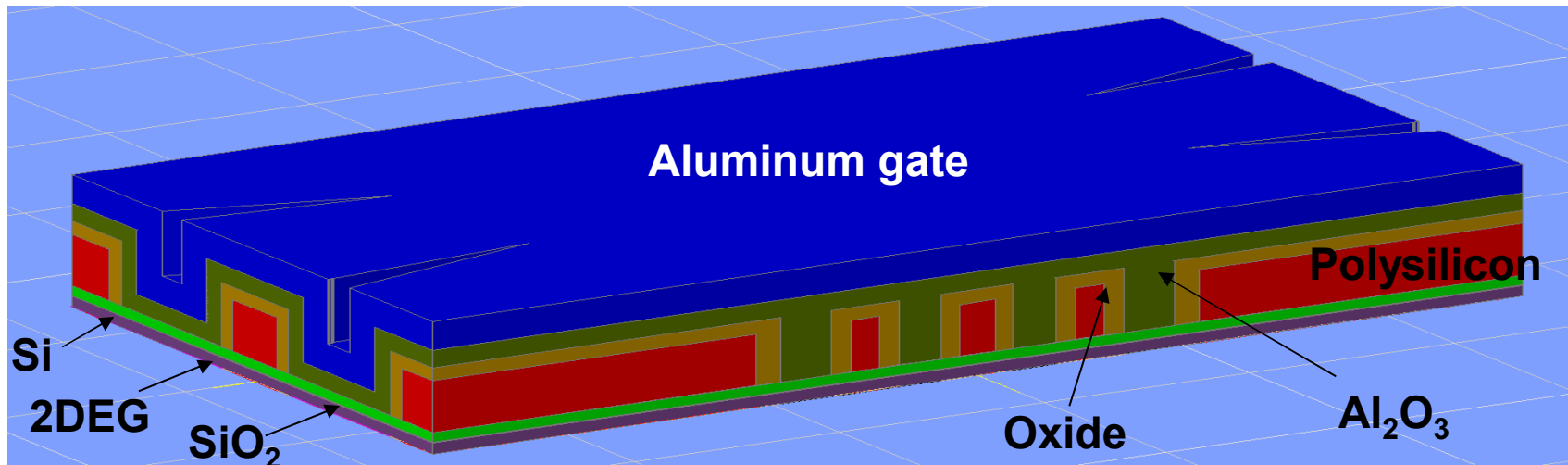
Positive slope = $C_{\text{GATE}} / (C_{\text{Total}} - C_{\text{S}})$
 Negative slope = $C_{\text{GATE}} / C_{\text{S}}$

Capacitance ratio



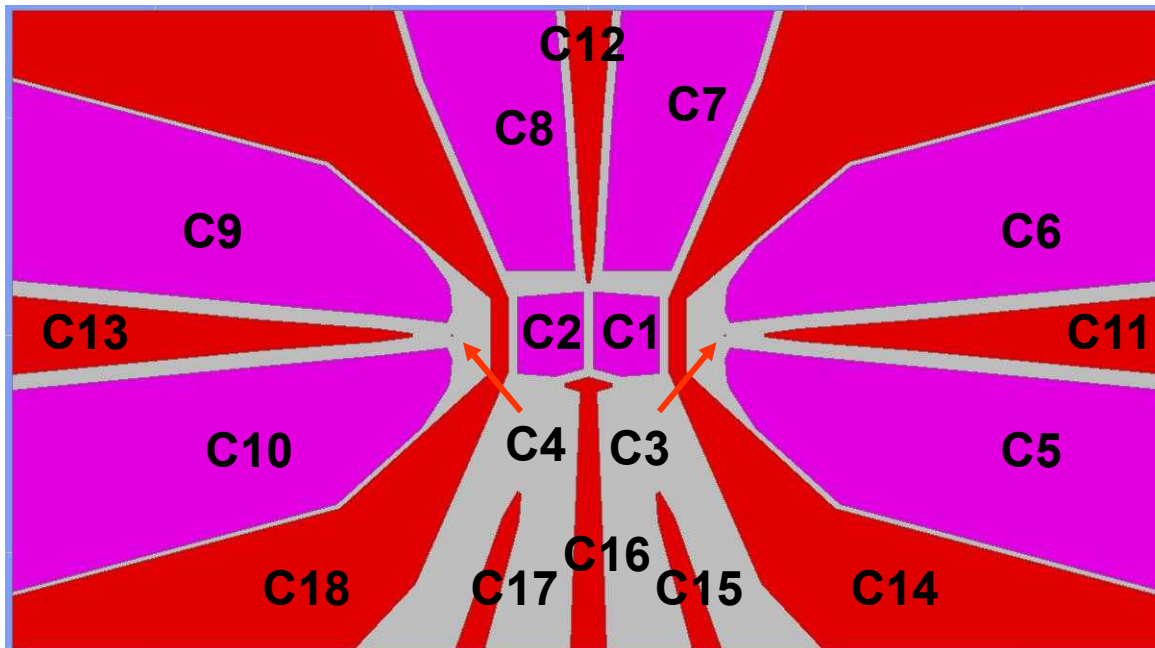
Ratio	Point B	Point A
$C_{\text{source}} / C_{\text{total}}$	0.436	0.378
$C_{\text{drain}} / C_{\text{total}}$	0.393	0.474
$C_{\text{wire}} / C_{\text{total}}$	0.014	0.019
$C_{\text{QPC}} / C_{\text{total}}$	0.134	0.099
$C_{\text{TG}} / C_{\text{total}}$	0.008	0.012
Total:	98.5%	98.2%

Electrostatic model



Density contours
in $1 \times 10^{11} \text{ cm}^{-2}$ increments
from 1×10^{11} to $1 \times 10^{12} \text{ cm}^{-2}$
 $V_{\text{tg}} = 18\text{V}$, all others = 0V

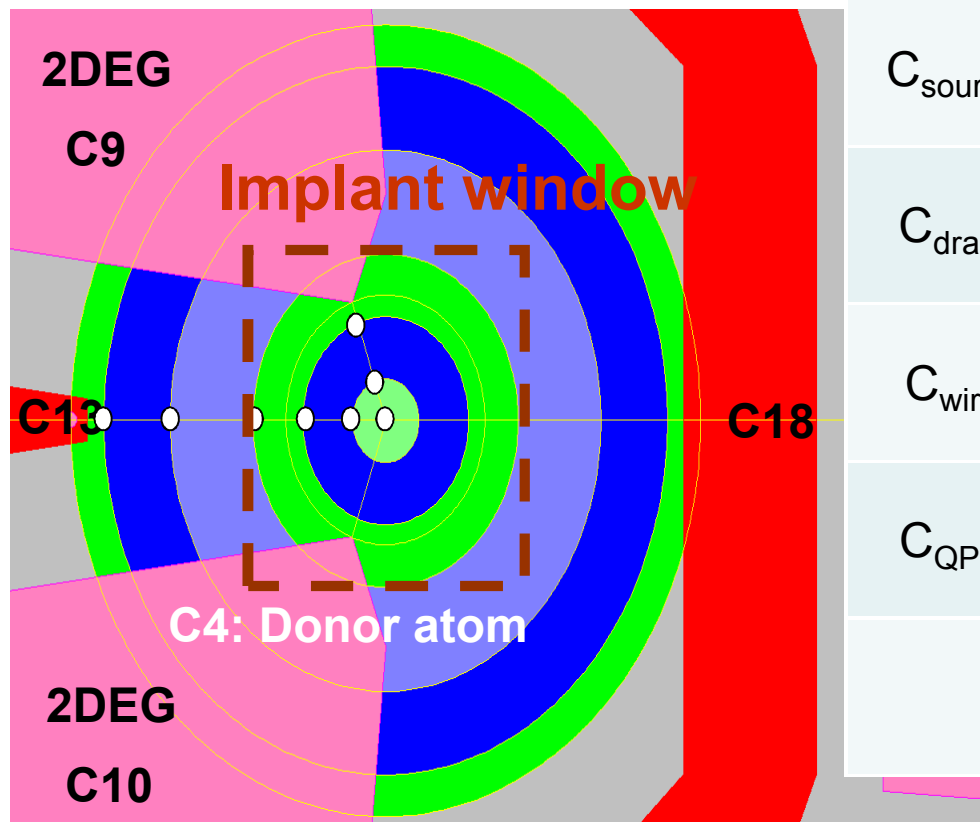
Capacitive model



	S438	(aF)		C3 & C4:		1.8nm	radius	Donor	Implant	10nm	depth	C1 & C2:		QD's	(RY's Sim)									
		QD	QD	Donor	Donor	2DEG-SE	2DEG-NE	2DEG-NNE	2DEG-NNW	2DEG-NW	2DEG-SW	E. QPC	V. Gate	W. QPC	E. Q	E. P.	C. P.	W. P.	W. Q	Top G				
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19				
QD	1	68.5917	-15.4877	-0.1204	-0.0204	-3.5873	-3.0517	-11.8335	-3.1399	-1.2549	-1.4843	-0.2484	-1.7458	-0.1214	-11.1903	-0.6631	-5.6034	-0.4491	-2.2456	-6.3446				
QD	2	-15.4877	68.4966	-0.0206	-0.1184	-1.4891	-1.2510	-3.1314	-11.8363	-3.0481	-3.5656	-0.1207	-1.7356	-0.2484	-2.2385	-0.4503	-5.5851	-0.6591	-11.1480	-6.3628				
Donor	3	-0.1204	-0.0206	2.7979	-0.0002	-0.8659	-0.8474	-0.1170	-0.0327	-0.0228	-0.0260	-0.0953	-0.0062	-0.0023	-0.4767	-0.0160	-0.0324	-0.0078	-0.0323	-0.0759				
Donor	4	-0.0204	-0.1184	-0.0002	2.7611	-0.0257	-0.0225	-0.0323	-0.1155	-0.8402	-0.8544	-0.0023	-0.0061	-0.0935	-0.0318	-0.0077	-0.0319	-0.0157	-0.4693	-0.0736				
2DEG-SE	5	-3.5873	-1.4891	-0.8659	-0.0257	391.2932	-51.9558	-6.7144	-3.5652	-3.6557	-4.4334	-51.6689	-0.5257	-0.4058	-108.6078	-3.9582	-4.2818	-1.4031	-5.1752	-138.9746				
2DEG-NE	6	-3.0517	-1.2510	-0.8474	-0.0225	-51.9558	386.4215	-16.3242	-4.7106	-3.6170	-3.6428	-51.5746	-0.8370	-0.3684	-106.2514	-1.4039	-2.1148	-0.8245	-4.4215	-133.1987				
2DEG-NNE	7	-11.8335	-3.1314	-0.1170	-0.0323	-6.7144	-16.3242	215.9327	-24.7744	-4.7113	-3.5555	-0.8729	-29.4635	-0.3973	-52.6689	-0.6863	-1.5295	-0.5767	-5.5480	-52.9642				
2DEG-NNW	8	-3.1399	-11.8363	-0.0327	-0.1155	-3.5652	-4.7106	-24.7744	215.6451	-16.3406	-6.6975	-0.3961	-29.3706	-0.8743	-5.5421	-0.5788	-1.5291	-0.6832	-52.4839	-52.9758				
2DEG-NW	9	-1.2549	-3.0481	-0.0228	-0.8402	-3.6557	-3.6170	-4.7113	-16.3406	386.3316	-51.8335	-0.3674	-0.8370	-51.6140	-4.4113	-0.8278	-2.1134	-1.4005	-106.4272	-133.0122				
2DEG-SW	10	-1.4843	-3.5656	-0.0260	-0.8544	-4.4334	-3.6428	-3.5555	-6.6975	-51.8335	390.2942	-0.4034	-0.5247	-51.8362	-5.1429	-1.4017	-4.2545	-3.9172	-108.7392	-137.9844				
E. QPC	11	-0.2484	-0.1207	-0.0953	-0.0023	-51.6689	-51.5746	-0.8729	-0.3961	-0.3674	-0.4034	316.8823	-0.0626	-0.0392	-7.8193	-0.2033	-0.2675	-0.1029	-0.4728	-202.1467				
V. Gate	12	-1.7458	-1.7356	-0.0062	-0.0061	-0.5257	-0.8370	-29.4635	-29.3706	-0.8370	-0.5247	-0.0626	198.2384	-0.0629	-3.2945	-0.0713	-0.3264	-0.0710	-3.2299	-125.8808				
W. QPC	13	-0.1214	-0.2484	-0.0023	-0.0935	-0.4058	-0.3684	-0.3973	-0.8743	-51.6140	-51.8362	-0.0392	-0.0629	317.2109	-0.4735	-0.1038	-0.2688	-0.2037	-7.9298	-202.2619				
E. Q	14	-11.1903	-2.2385	-0.4767	-0.0318	-108.6078	-106.2514	-52.6689	-5.5421	-4.4113	-5.1429	-7.8193	-3.2945	-0.4735	930.5588	-30.1907	-12.0956	-1.8729	-6.4402	-571.5868				
E. P.	15	-0.6631	-0.4503	-0.0160	-0.0077	-3.9582	-1.4039	-0.6863	-0.5788	-0.8278	-1.4017	-0.2033	-0.0713	-0.1038	-30.1907	99.2164	-21.9354	-1.2404	-1.8864	-33.5535				
C. P.	16	-5.6034	-5.5851	-0.0324	-0.0319	-4.2818	-2.1148	-1.5295	-1.5291	-2.1134	-4.2545	-0.2675	-0.3264	-0.2688	-12.0956	-21.9354	175.0828	-21.8002	-12.0778	-79.3580				
W. P.	17	-0.4491	-0.6591	-0.0078	-0.0157	-1.4031	-0.8245	-0.5767	-0.6832	-1.4005	-3.9172	-0.1029	-0.0710	-0.2037	-1.2404	-21.8002	99.1811	-30.2491	-33.5721	-571.4622				
W. Q	18	-2.2456	-11.1480	-0.0323	-0.4693	-5.1752	-4.4215	-5.5480	-52.4839	-106.4272	-108.7392	-0.4728	-3.2299	-7.9298	-6.4402	-1.8864	-12.0778	-30.2491	930.6425	-571.4622				
Top G	19	-6.3446	-6.3628	-0.0759	-0.0736	-138.9746	-133.1987	-52.9642	-52.9758	-133.0122	-137.9844	-202.1467	-125.8808	-202.2619	-571.5868	-33.5535	-79.3580	-33.5721	-571.4622	2481.7889				

with Harold Stalford, Ralph Young

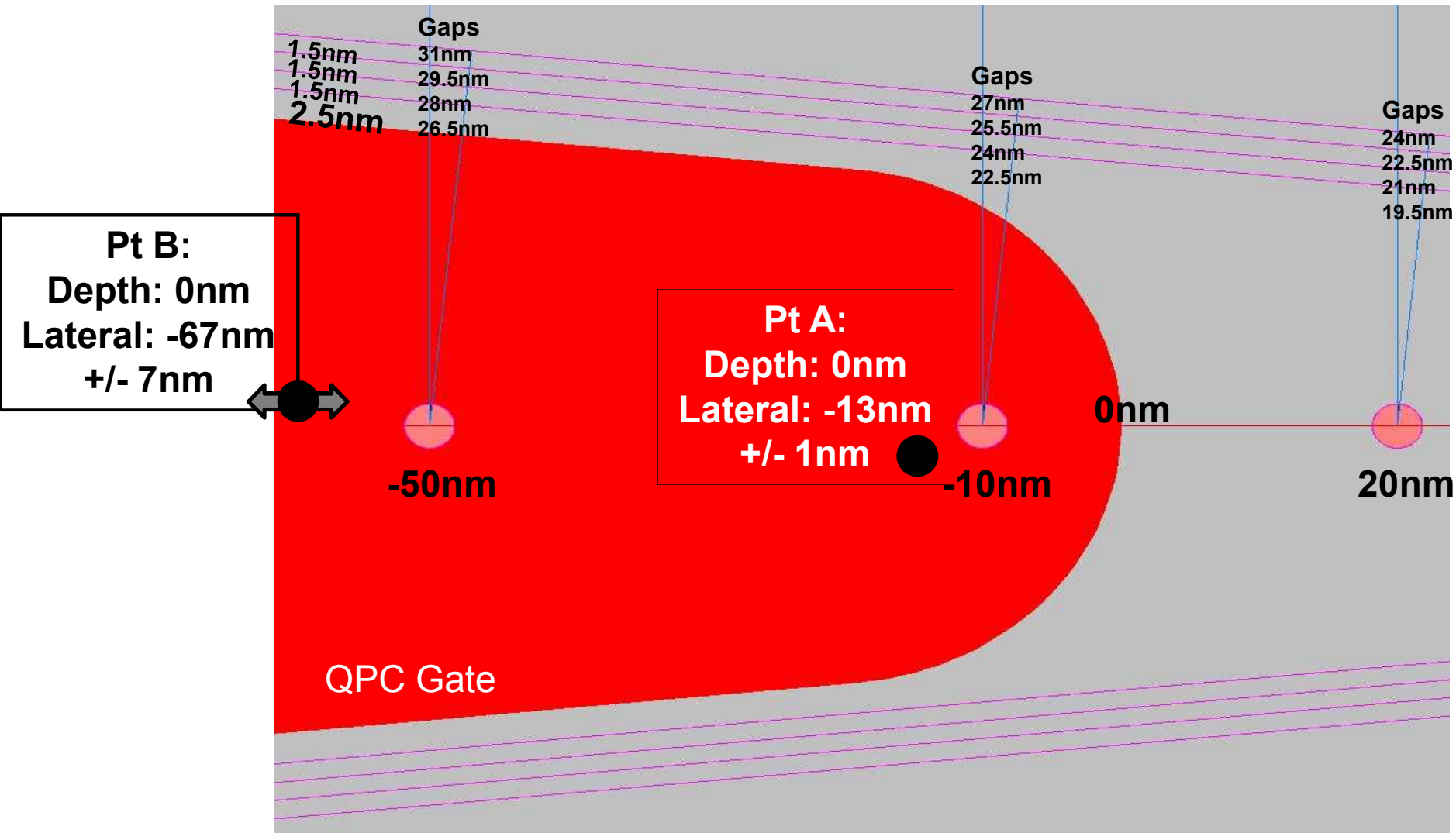
Capacitive results



Ratio	Point B		Point A	
	Expt.	Sim.	Expt.	Sim.
$C_{\text{source}} / C_{\text{total}}$	0.436	0.435	0.378	0.379
$C_{\text{drain}} / C_{\text{total}}$	0.393	0.392	0.474	0.473
$C_{\text{wire}} / C_{\text{total}}$	0.014	0.013	0.019	0.019
$C_{\text{QPC}} / C_{\text{total}}$	0.134	0.132	0.099	0.095
Total:	0.985		0.982	

with Harold Stalford,
Ralph Young

Pts A & B Dot Locations



Conclusions

- In implanted devices, we must decide whether tunneling resonances are due to donors or defects.
- Capacitive measurements locate the resonant states in the point contact with high confidence.
- Applicable to all systems, for donor or gate-defined quantum dots.

Acknowledgements

Quantum Team:

Ed Bielejec
Steve Carr
Malcolm Carroll
Kent Childs
Kevin Eng
Robert Grubbs
Paul Hines
Mike Lilly
TzuMing Lu
Joel Means
Rick Muller
Eric Nordberg
Tammy Pluym
Rajib Rahman
Bev Silva
Harold Stalford
Jeff Stevens
Tom Tarman
Greg Ten Eyck

Quantum team cont'd:

Denise Tibbetts
Lisa Tracy
Joel Wendt
Wayne Witzel
Ralph Young

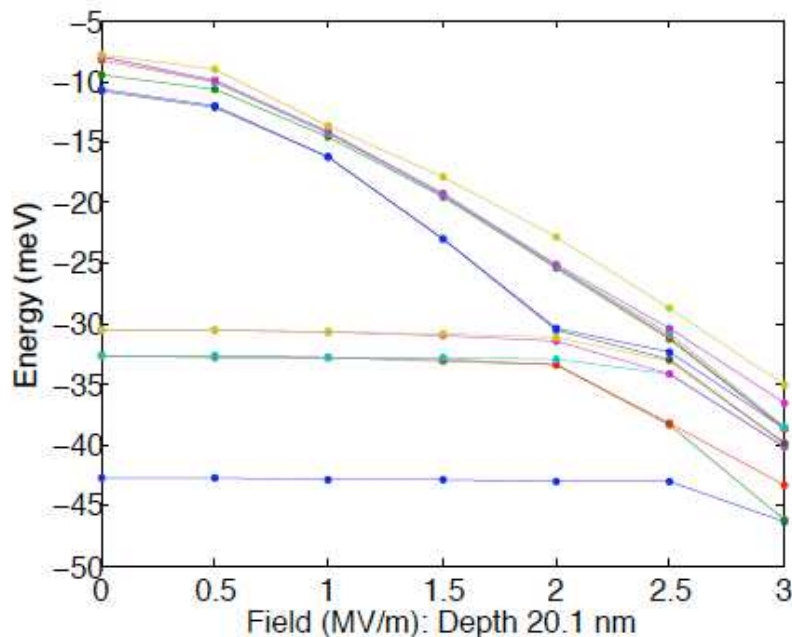
Australian collaborators:

Susan Angus
Andrea Morello
Andrew Dzurak
Dan Tomlinson
William Lee
Michelle Simmons

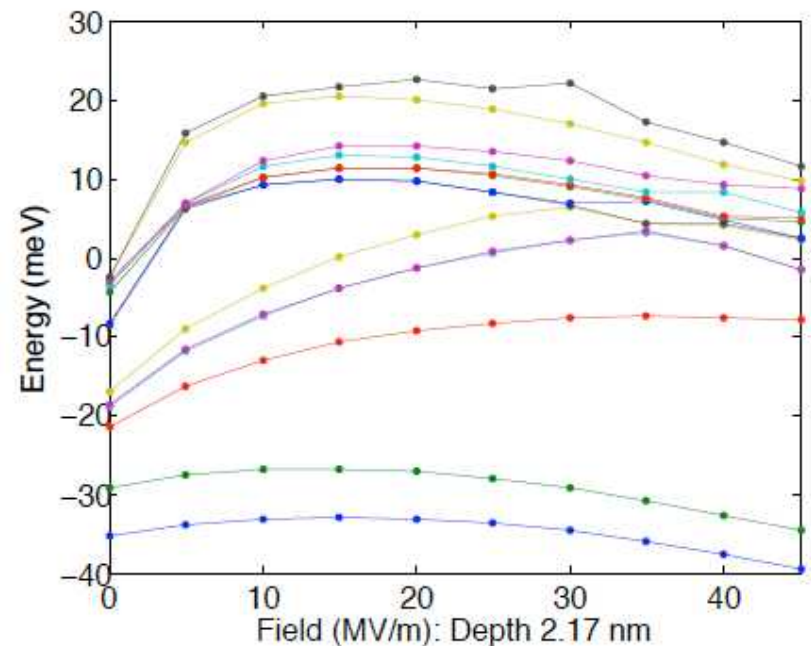


Spectroscopy: Stark shifts

Deeply buried donor



Donor near interface



Previous work

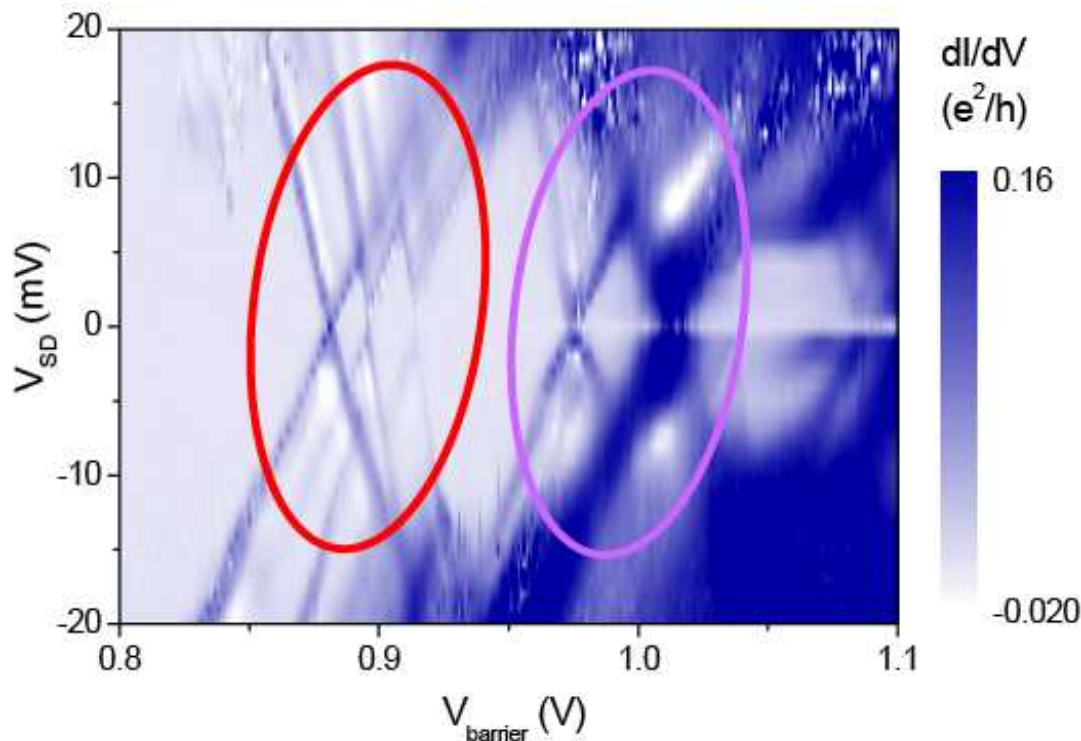
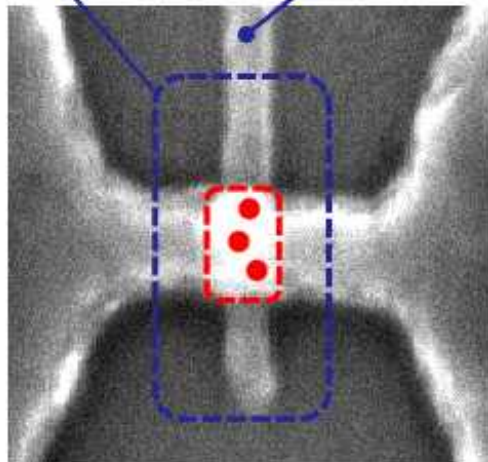
timed P-implant

$\langle n \rangle = 3$
in 50×30 nm

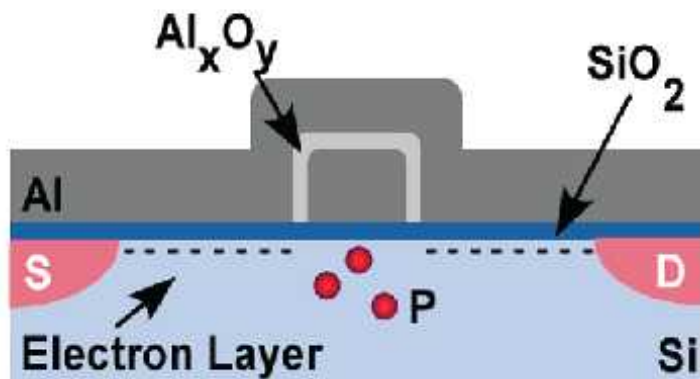
barrier/donor
gate

P-implant area

V_{barrier}

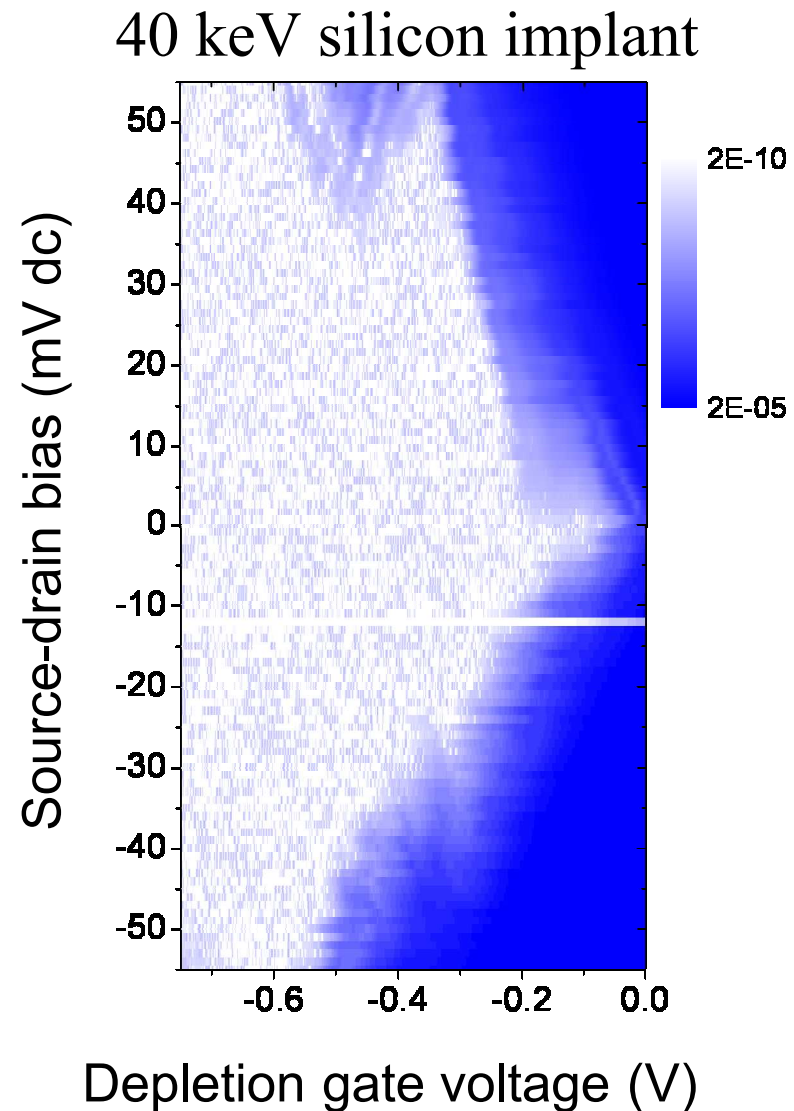
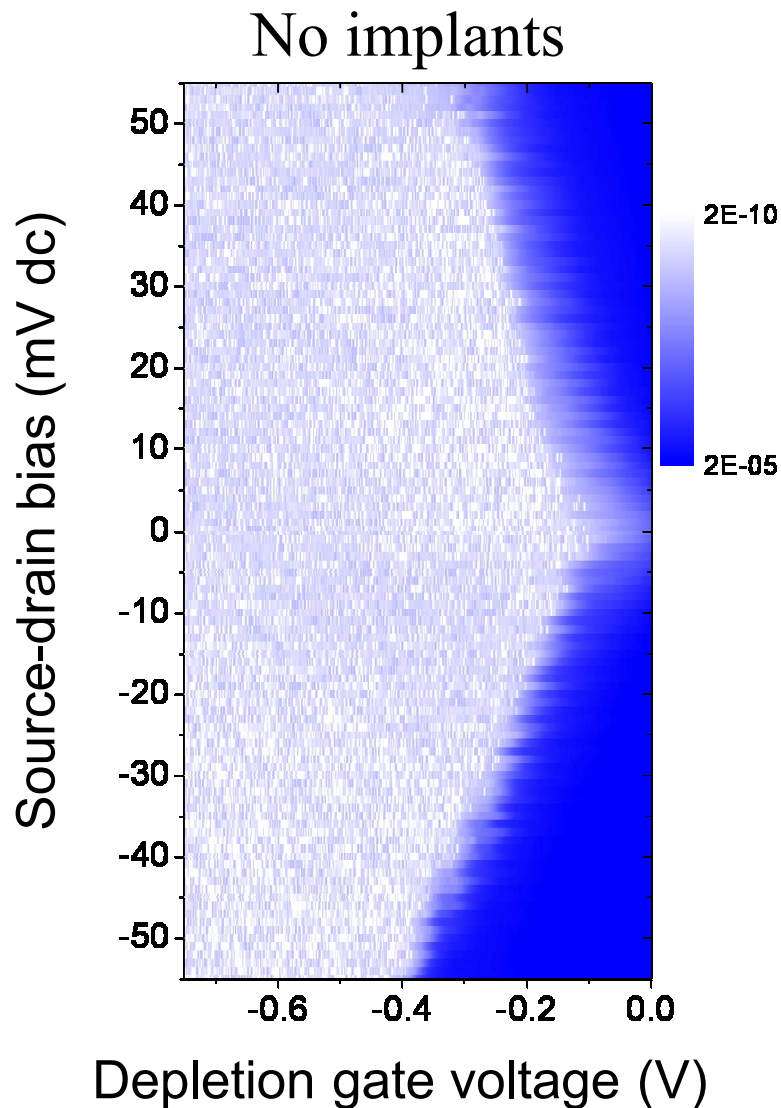


Tan et al., Nano Lett. 2010



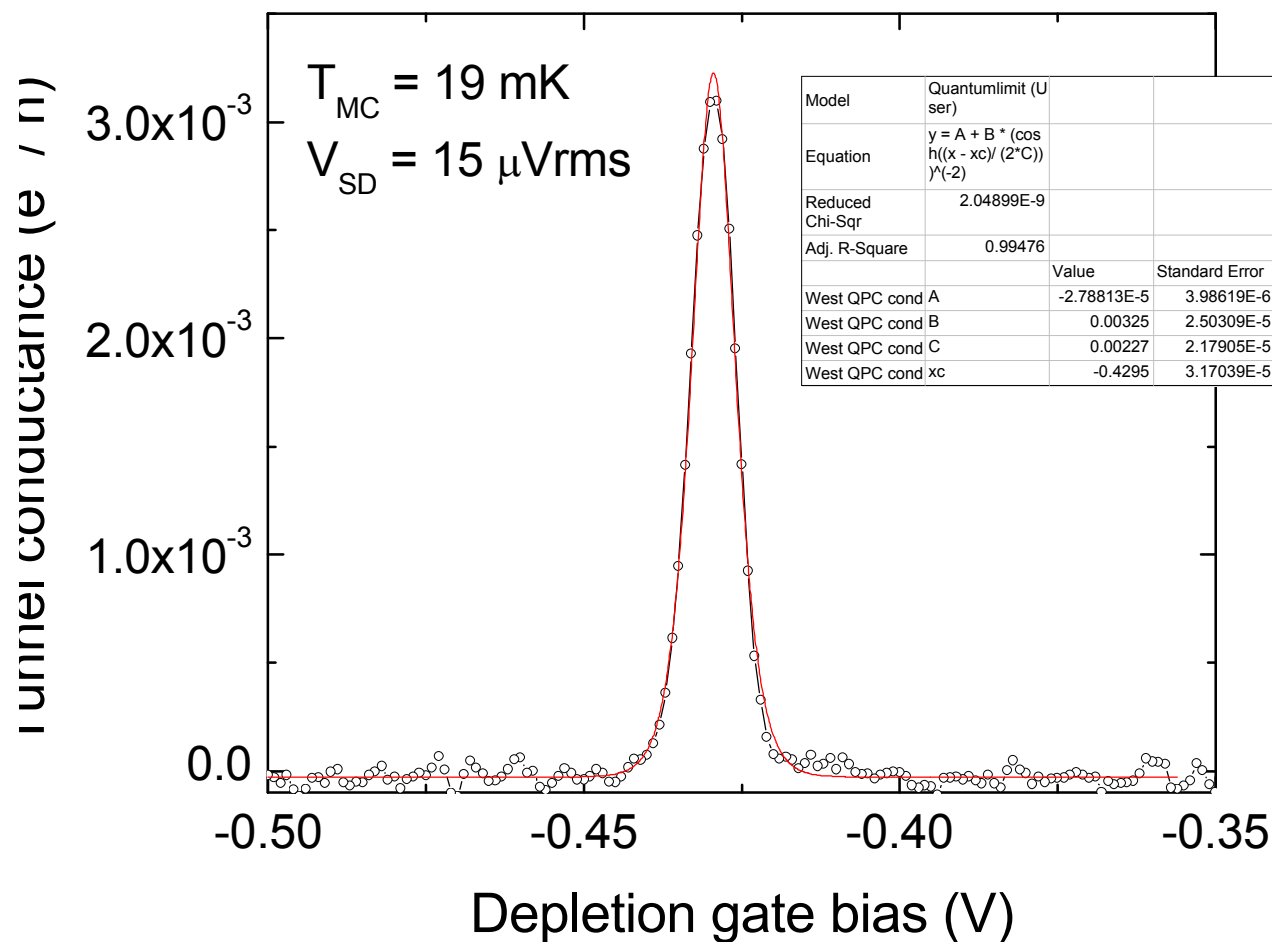
Long coherence times in Si:P
 $T_2 = 0.6$ seconds.

Control sample: Silicon implant



Lever arm analysis

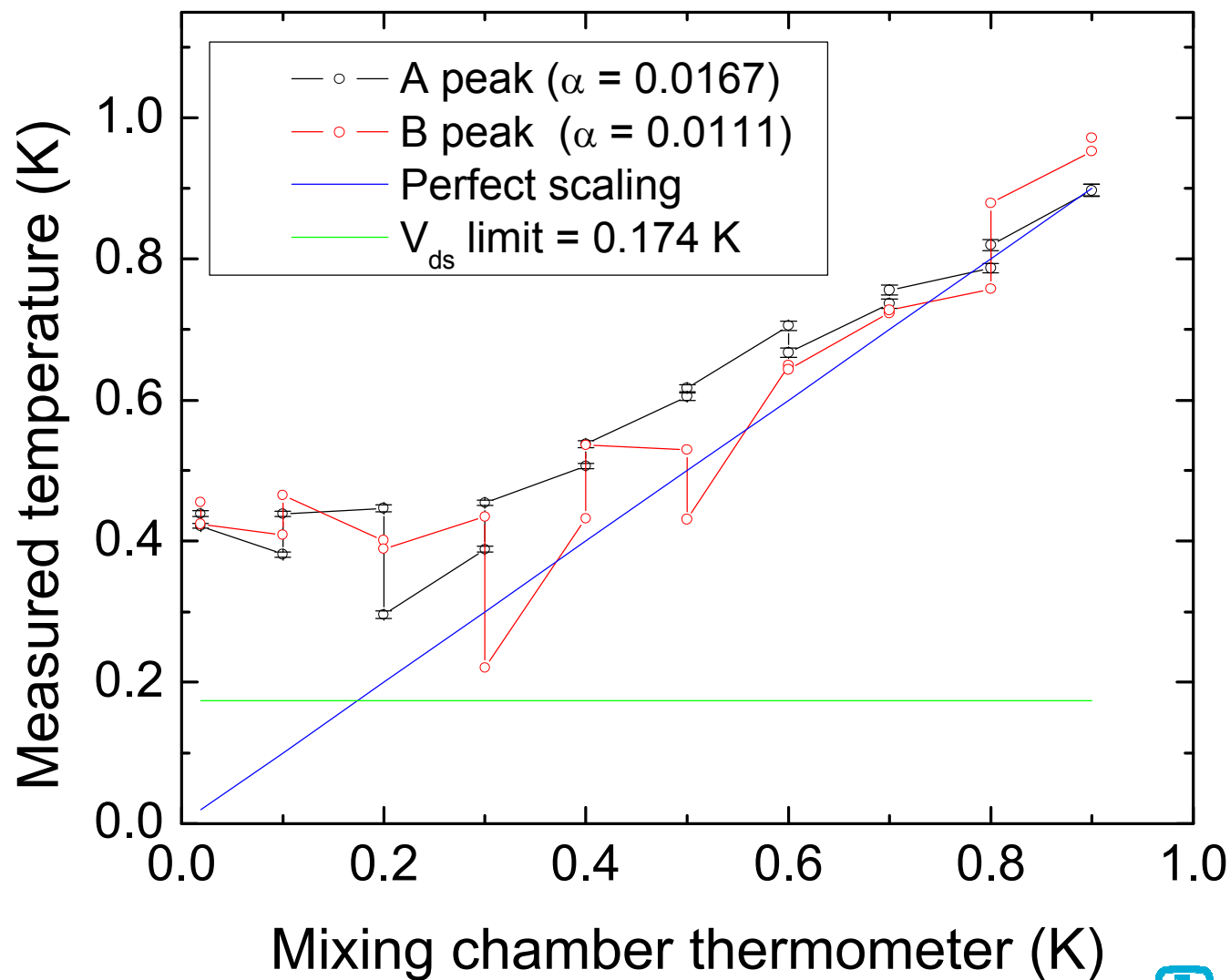
$$\frac{G}{G_{MAX}} = \frac{\Delta E}{4k_B T} \cosh^{-2} \left(\frac{\alpha(V - V_0)}{2k_B T_{measured}} \right)$$



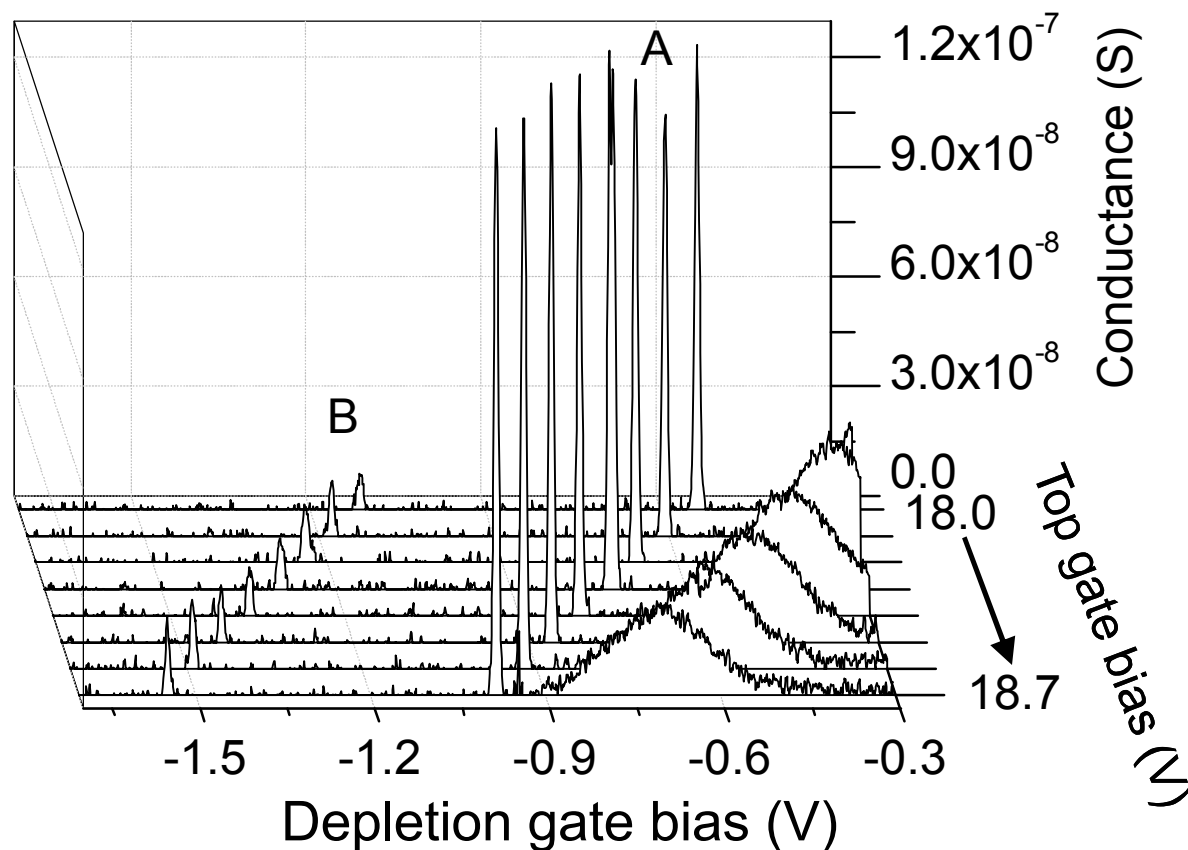
$$\alpha = \frac{eC_G}{C_\Sigma}$$

$$\alpha = \frac{2k_B T_{measured}}{\delta V}$$

Lever arm analysis



Top gate lever arm

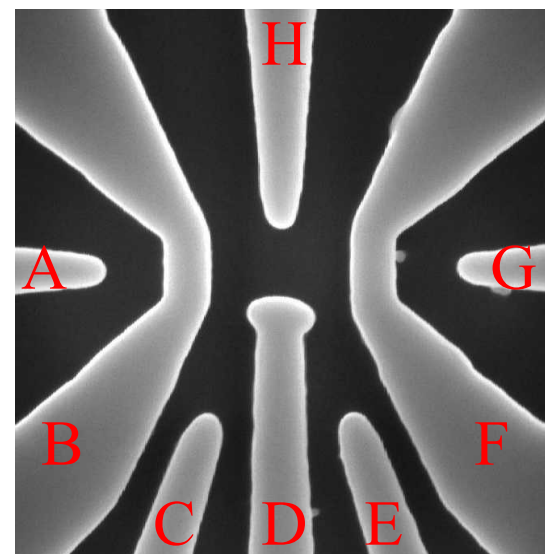


A slope:

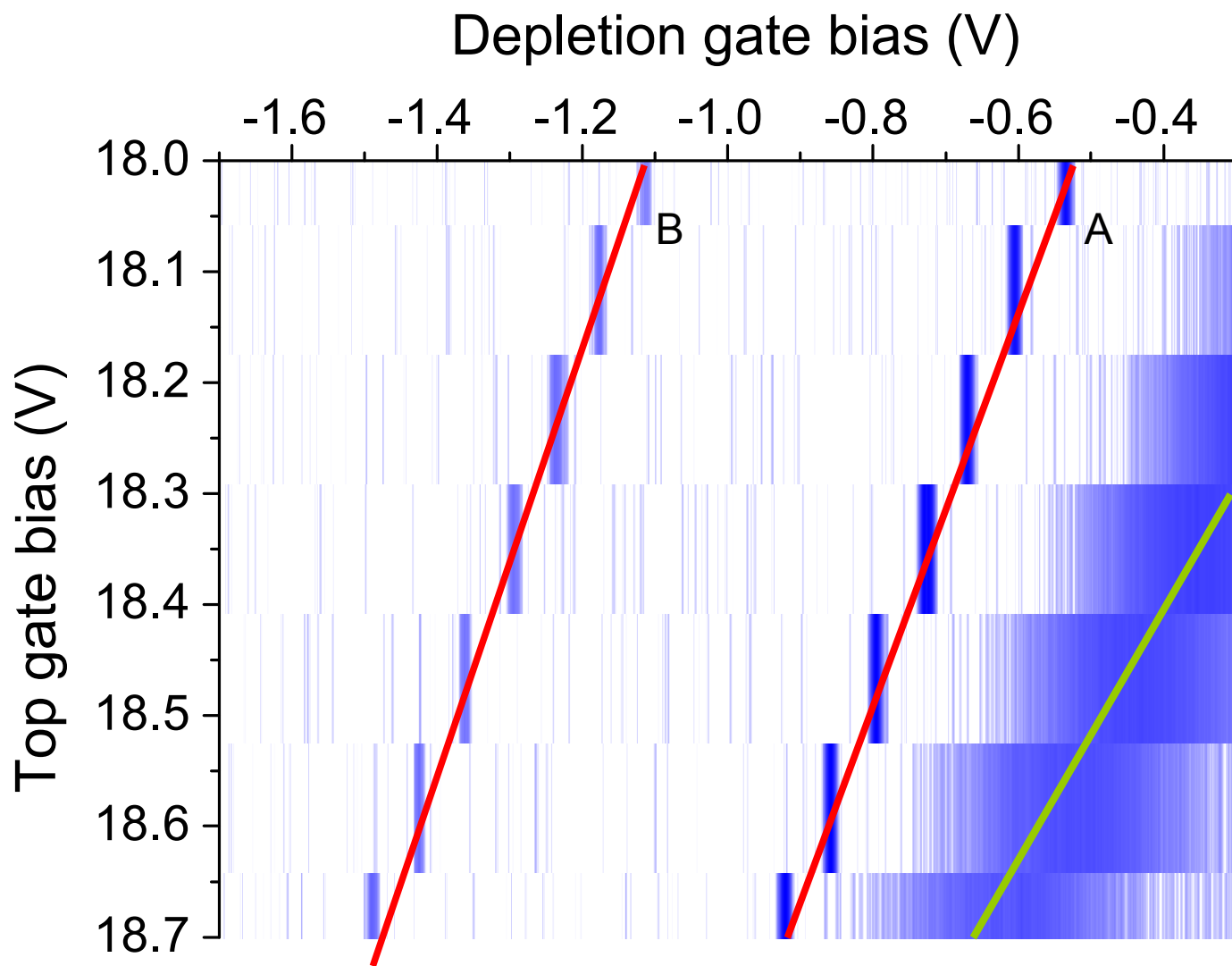
$$dV_{\text{Poly}} / dV_{\text{TG}} = -0.639$$

B slope:

$$dV_{\text{Poly}} / dV_{\text{TG}} = -0.625$$



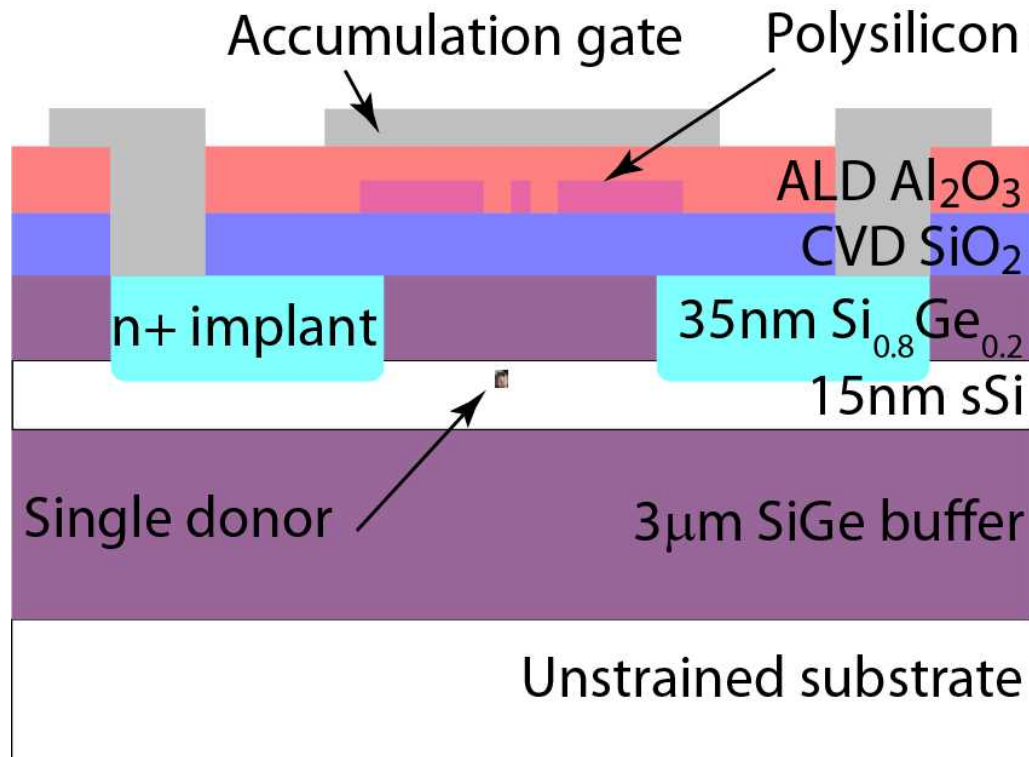
Top gate lever arm



A and B have nearly identical top gate lever arm.
There is a disorder dot that does have a larger lever arm.

Disorder dot!

Advantages of Si-SiGe interface

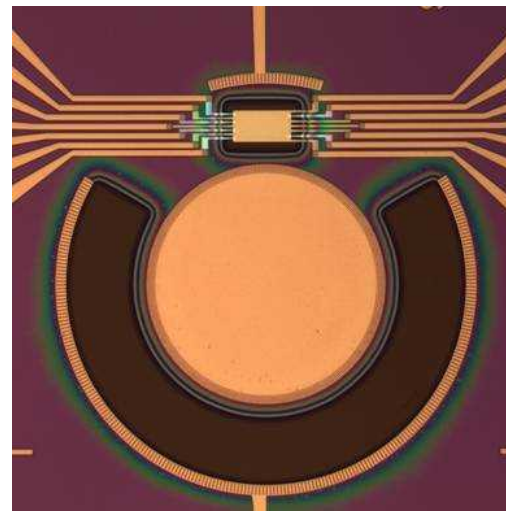
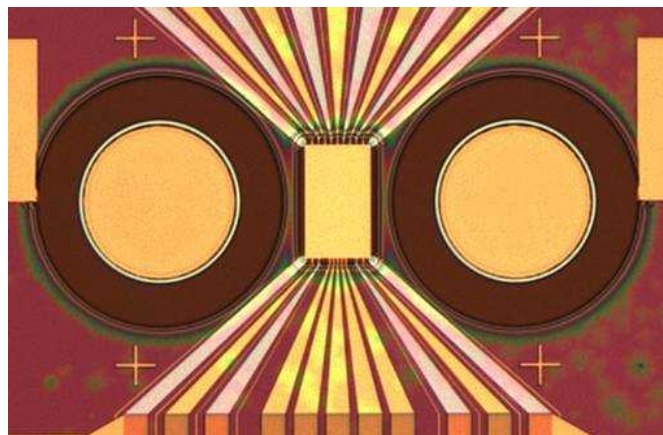


Film stack showing goal: DQD with SiGe dielectric on relaxed SiGe buffer layer.

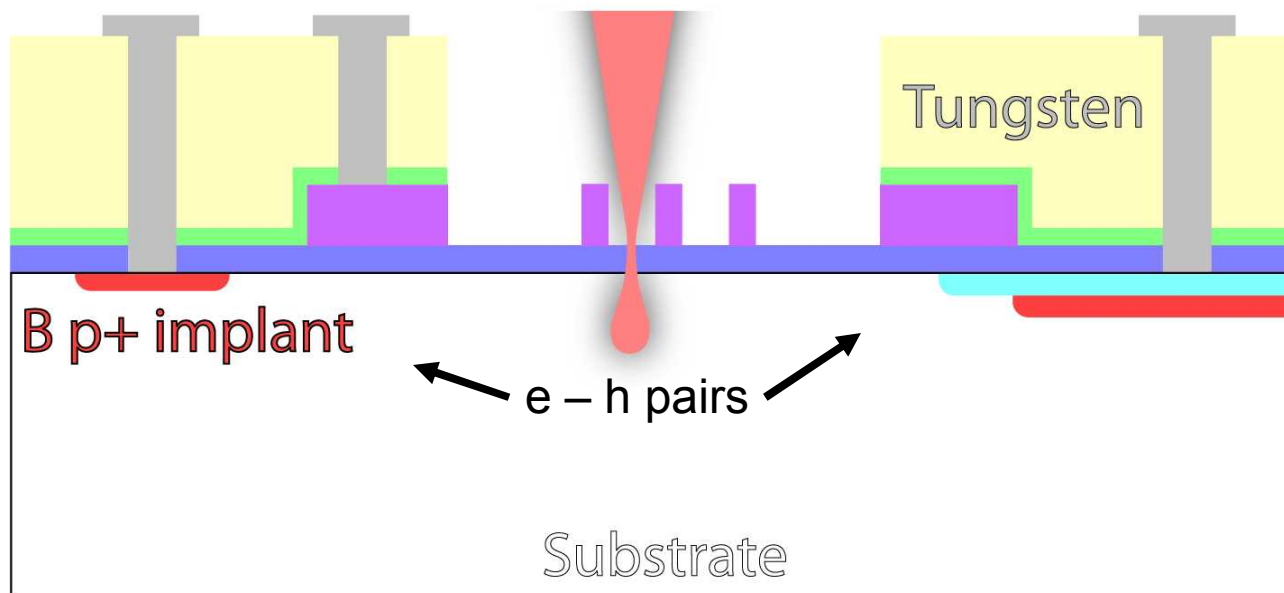
1. sSOI allows us to integrate SiGe dielectrics into our normal MOSFET process.
2. SiGe dielectric constant higher than SiO_2 , lowering gate voltages.
3. Si-SiGe interface is clean, reducing charge noise.
4. Electron g-factor differs in Si and SiGe, potentially allowing controlled spin rotations.

sSOI substrate characterization for STM donor lithography, with SiGe dielectric. Collaboration with Michelle Simmons, and new STM litho program at Sandia!

Detecting single dopant atoms



Ion beam

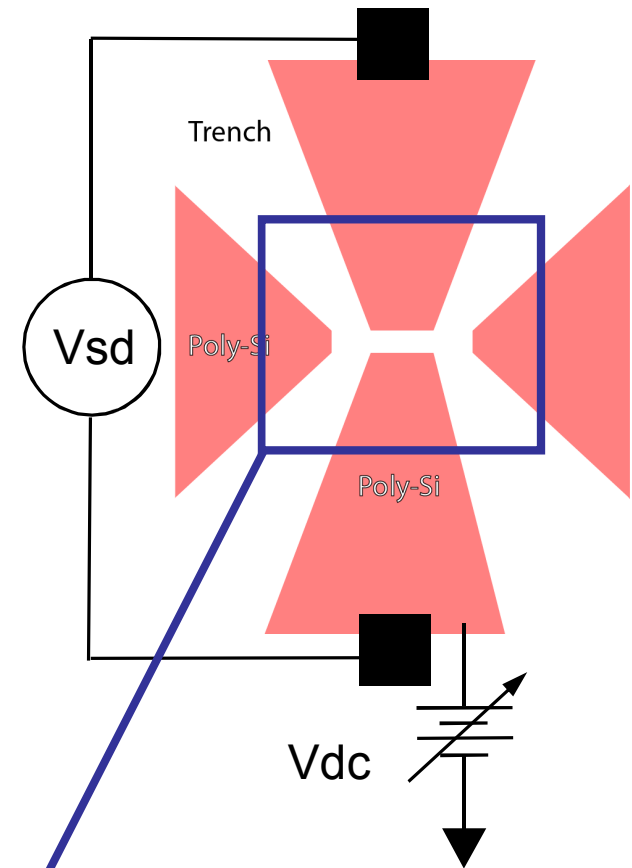
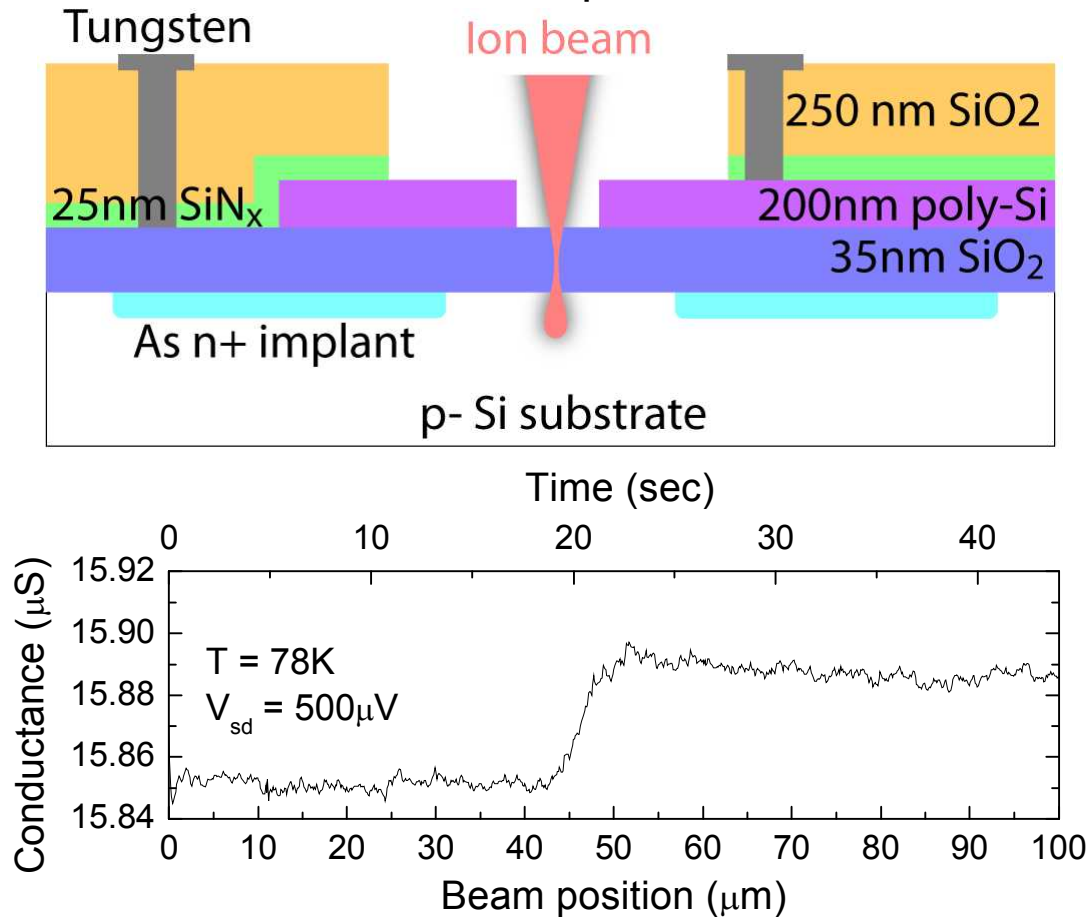


250 nm SiO₂
25nm SiN_x
200nm poly-Si
10nm SiO₂
As n+ implant
B p implant

Use the device as a detector

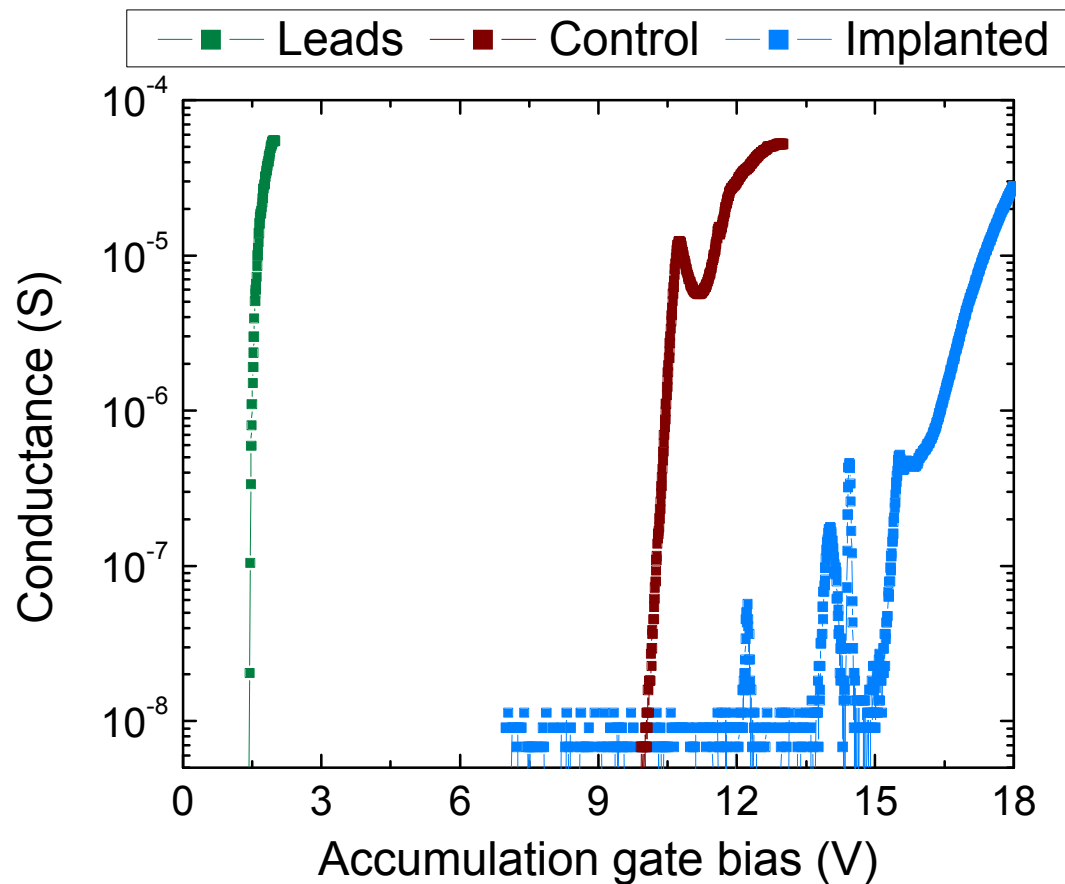
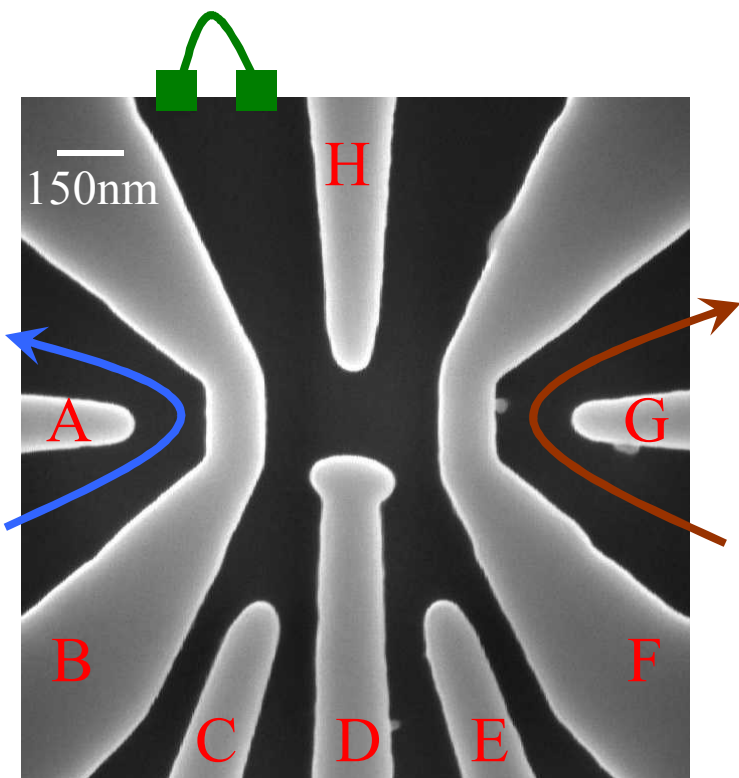
250 keV protons

Ion beam



Proton beam raster window

Threshold difference



Implant damage increases interface trap density and fixed charge, but mostly repaired after high temperature processing.

Ion implant damage

45 keV silicon implant, equivalent to 100 keV antimony implant

900 C furnace anneal, 24 minutes in O₂

Interface Trap Density vs. Trap Energy

